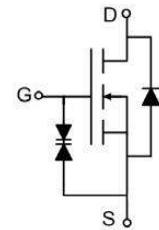
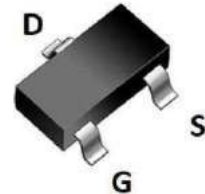


Features

- N-Channel
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired
- ESD Rating: HBM 2KV

V_{DS}	20	V
$R_{DS(on),TYP@ V_{GS}=4.5V}$	12.3	Ω
$R_{DS(on),TYP@ V_{GS}=2.5V}$	15.6	Ω
I_D	7.2	A

SOT-23


Part ID	Package Type	Marking	Packing
ZT3416	SOT-23	3416	3000pcs/Reel

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 10	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	20	V	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_C = 25^\circ\text{C}$ 28.8	A	
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous	$T_C = 25^\circ\text{C}$	7.2	A
		$T_C = 100^\circ\text{C}$	4.5	A
P_D	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	1.33	W
		$T_C = 100^\circ\text{C}$	0.53	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	93	$^\circ\text{C/W}$	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 2)	25	mJ	

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V	--	--	10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	--	1.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =5A	--	12.3	16	mΩ
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =4A	--	15.6	20.6	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHz	--	666	--	pF
C _{oss}	Output Capacitance		--	148	--	pF
C _{rss}	Reverse Transfer Capacitance		--	88	--	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =5A, V _{GS} =4.5V	--	9	--	nC
Q _{gs}	Gate-Source Charge		--	1.5	--	nC
Q _{gd}	Gate-Drain Charge		--	1.9	--	nC
Switching Characteristics						
T _{d(on)}	Turn-on Delay Time	V _{DS} =10V, R _L =2Ω, R _G =3Ω, V _{GS} =4.5V	--	10	--	ns
T _r	Turn-on Rise Time		--	33	--	ns
T _{d(off)}	Turn-Off Delay Time		--	54	--	ns
T _f	Turn-Off Fall Time		--	50	--	ns
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _{SD}	Source-Drain Current (Body Diode)		--	--	7.2	A
V _{SD}	Forward on voltage (Note 3)	I _S =5A, V _{GS} =0V	--	--	1.2	V

Notes:

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2.E_{AS} condition: T_J=25°C, V_{DD}=10V, V_G=10V, R_G=25Ω, L=0.5mH.
- 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

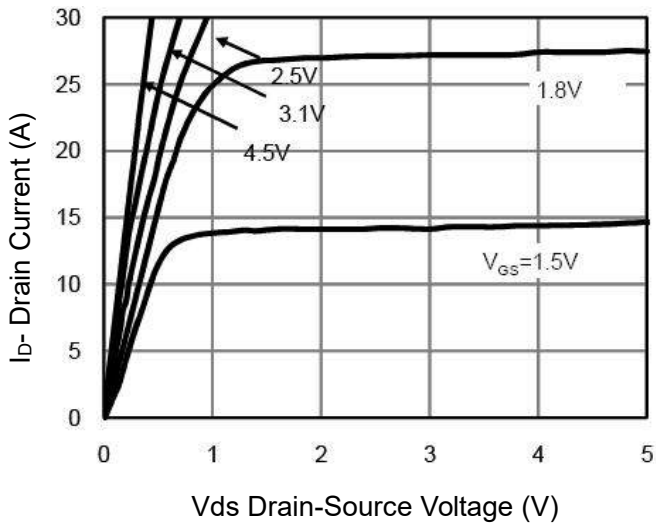


Figure 1. Output Characteristics

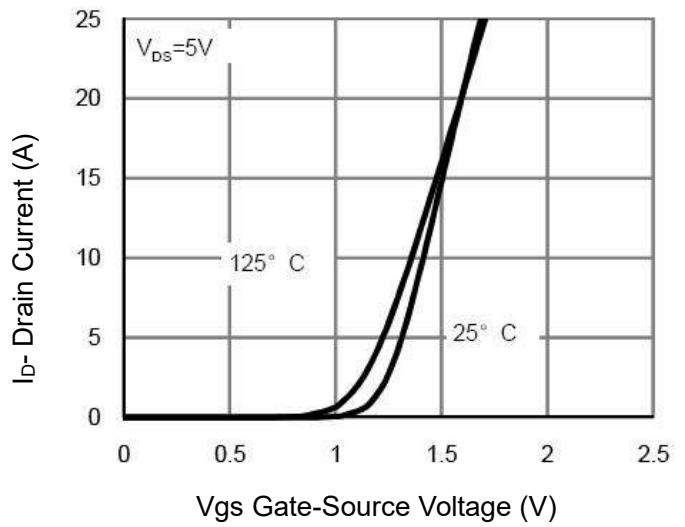


Figure 2. Transfer Characteristics

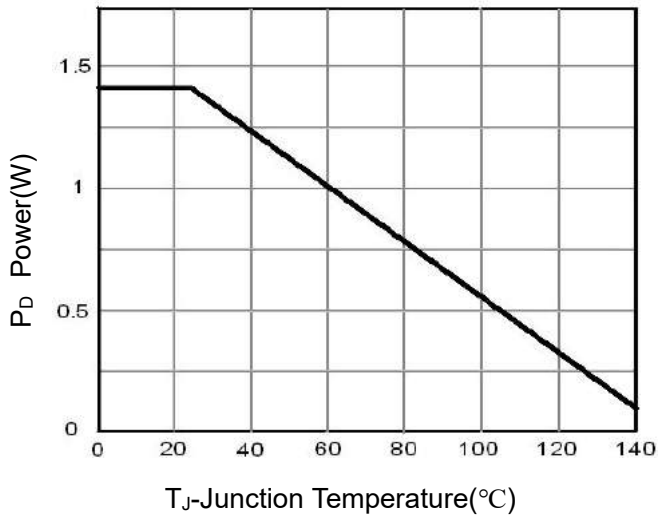


Figure 3. Power Dissipation

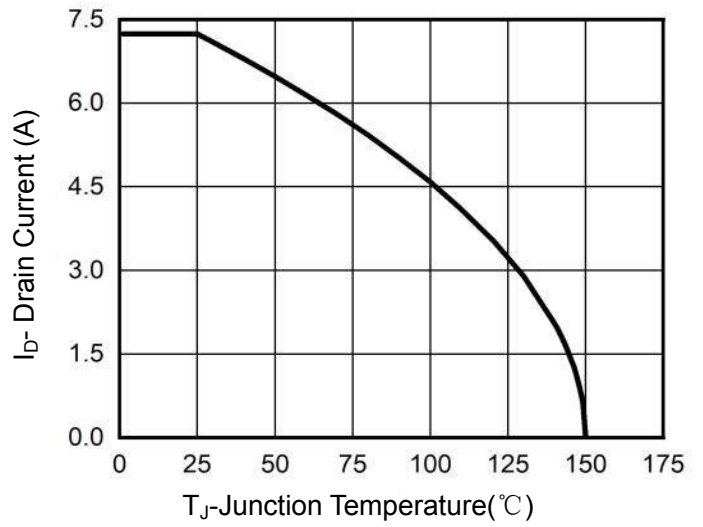


Figure 4. Drain Current

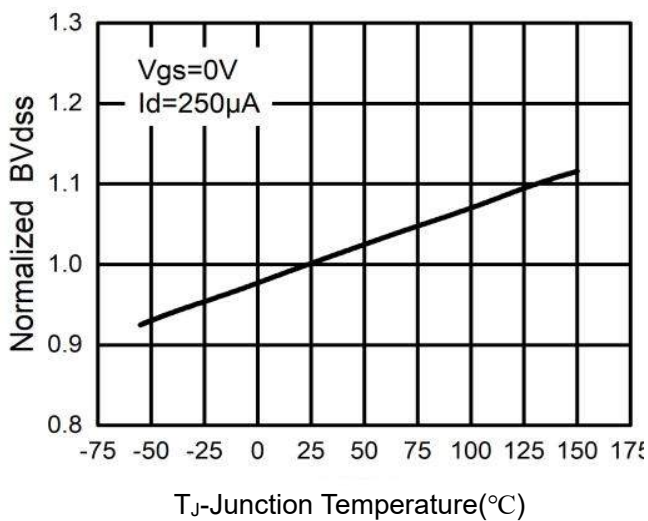


Figure 5. BV_{DSS} vs Junction Temperature

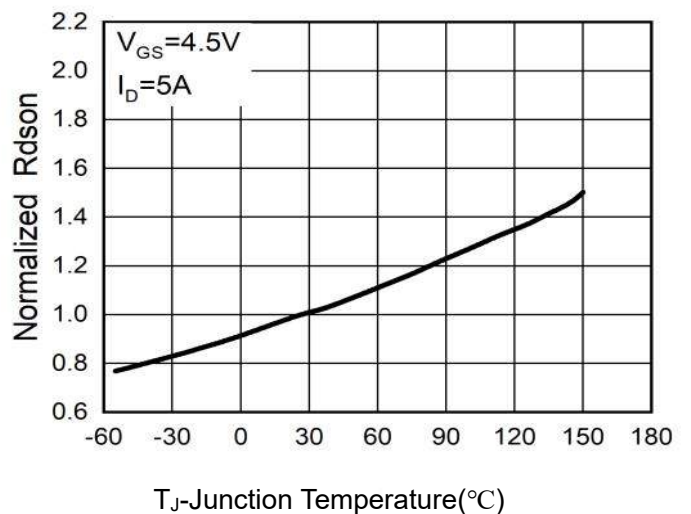


Figure 6. $R_{DS(ON)}$ vs Junction Temperature

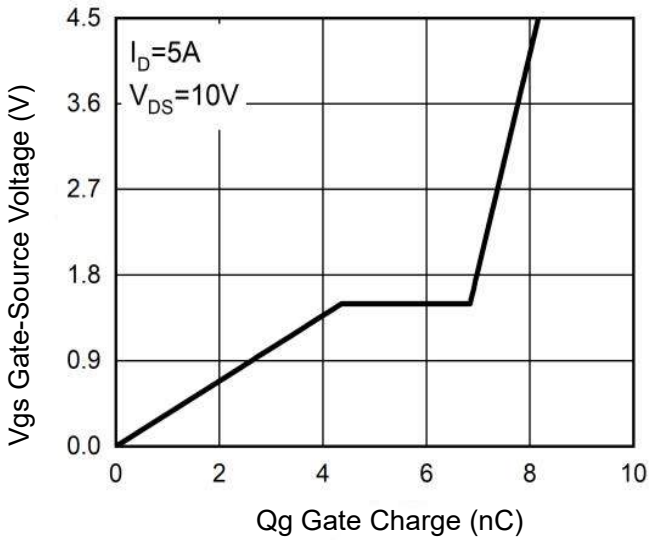


Figure 7. Gate Charge Waveforms

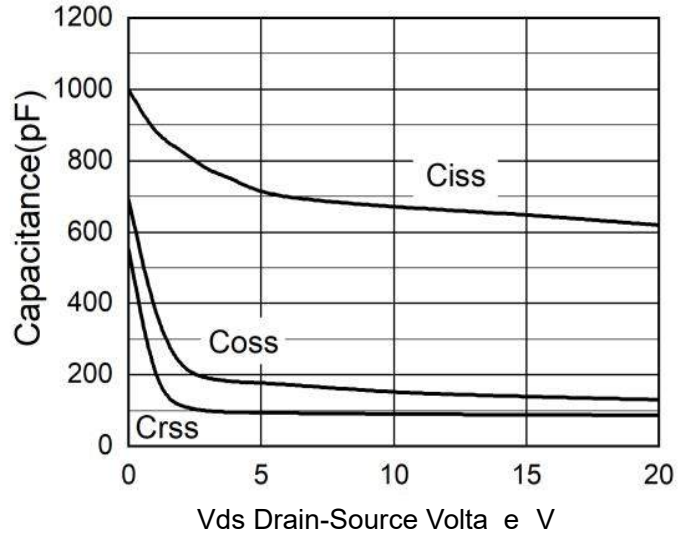


Figure 8. Capacitance

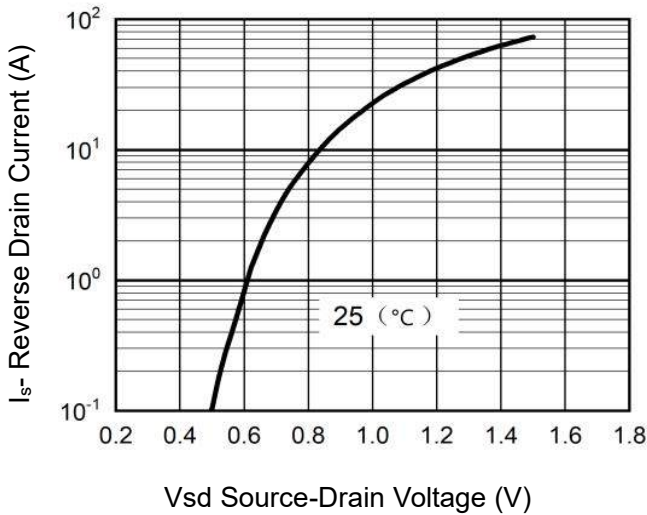


Figure 9. Body-Diode Characteristics

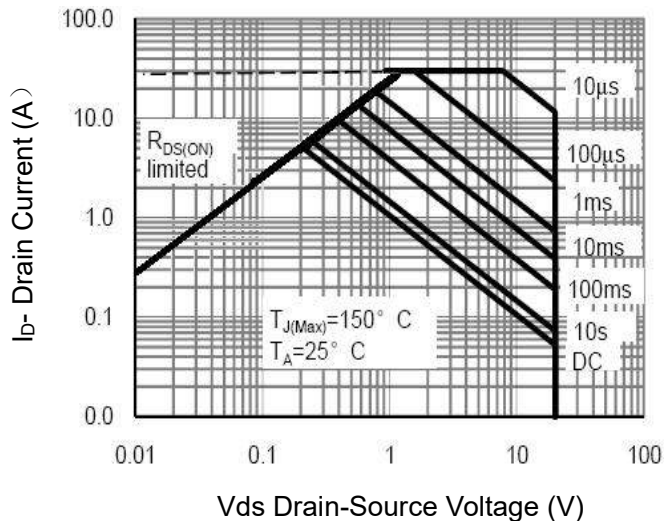


Figure 10. Maximum Safe Operating Area

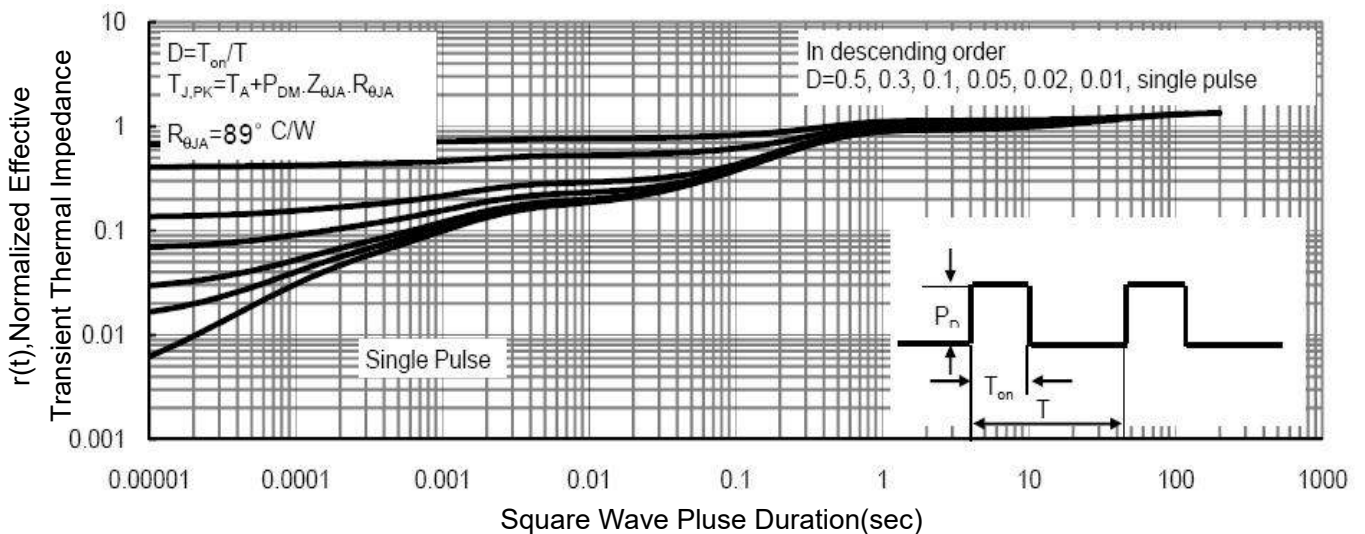


Figure 11 Normalized Maximum Transient Thermal Impedance

Test Circuit

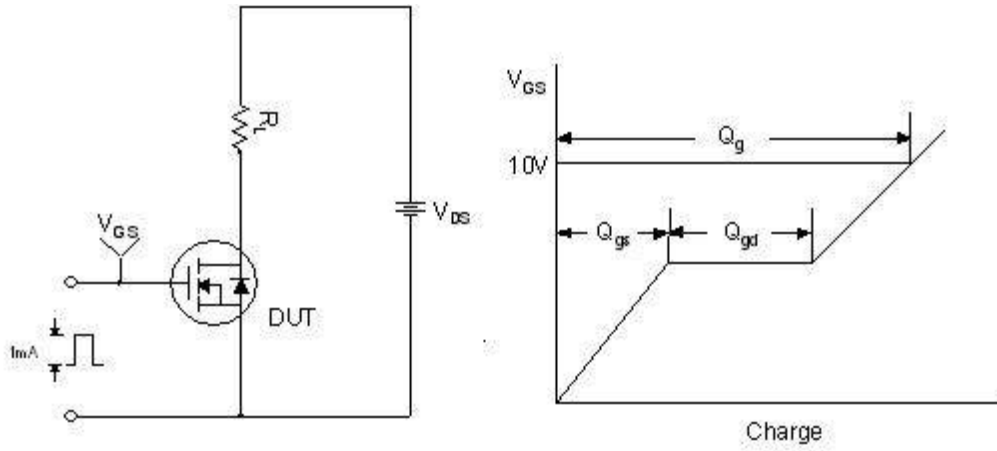


Figure 1. Gate Charge Test Circuit & Waveform

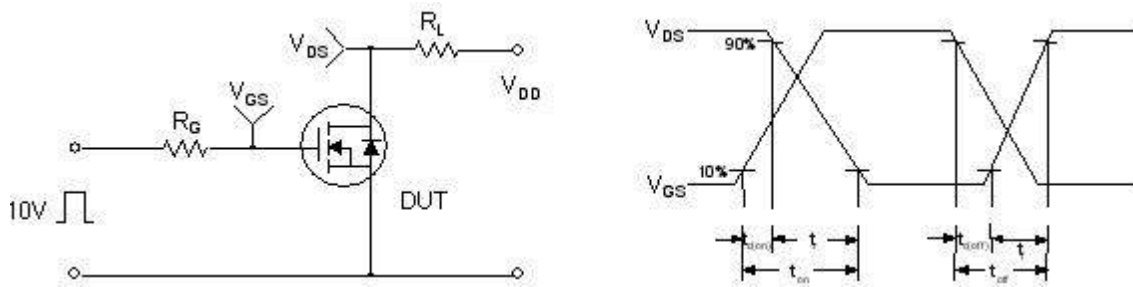


Figure 2. Resistive Switching Test Circuit & Waveforms

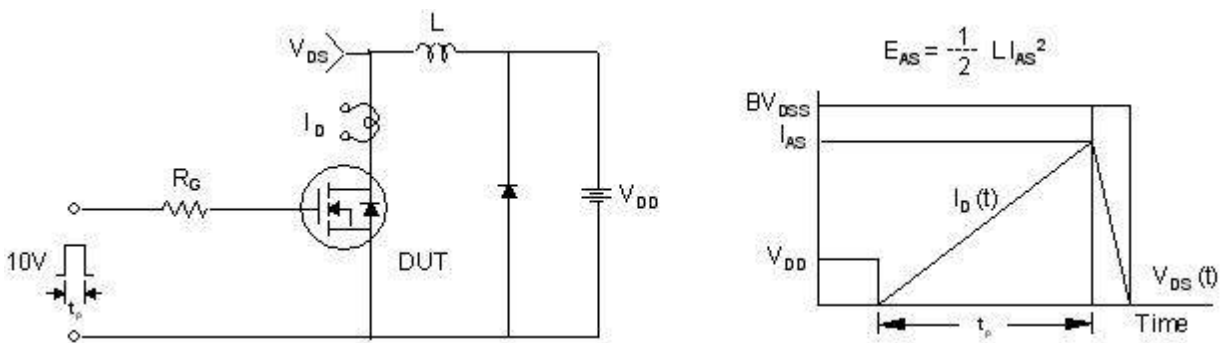
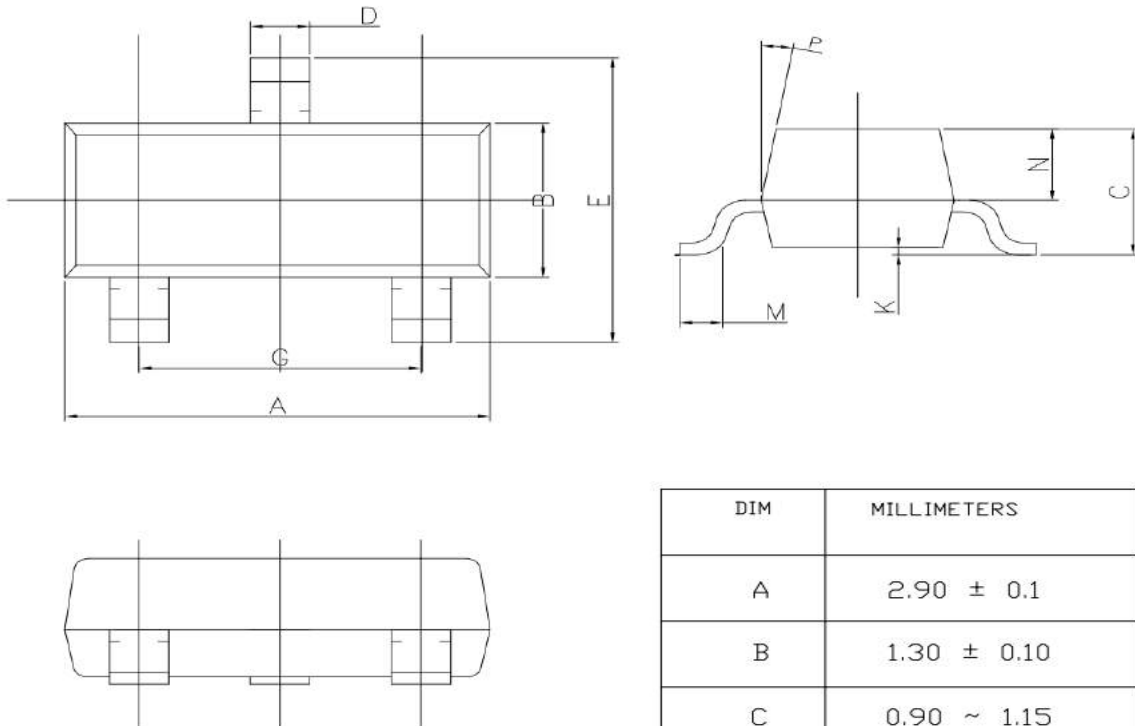


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms

SOT-23 Package Information



DIM	MILLIMETERS
A	2.90 ± 0.1
B	1.30 ± 0.10
C	0.90 ~ 1.15
D	0.40 ± 0.1
E	2.40 ± 0.15
G	1.90 ± 0.10
K	0.00~0.10
M	0.30MIN
N	0.60 ± 0.10
P	10°TYP

Customer Service

Sales and Service:

zj@ztasemi.com